

ABSTRACT OF THE DISCLOSURE

A polishing apparatus is used for polishing a workpiece such as a semiconductor wafer to a flat mirror finish. The polishing apparatus includes a turntable having polishing surface, a top ring for holding a workpiece and pressing the workpiece against the polishing surface to polish the workpiece. The polishing apparatus further includes a rotary transporter disposed in a position which can be accessed by the top ring and having a plurality of stages positioned on a predetermined circumference from a center of rotation of the rotary transporter for holding the workpieces. The polishing apparatus further includes a plurality of support tables removably held by the respective stages of the rotary transporter for supporting the workpieces, and a pusher for transferring the workpiece between the support table and the top ring.

This Sheet Has Been Replaced

